RYZ024A and RA MCU

Firmware Upgrade from Host MCU

Introduction

This document describes a sample application that upgrades the RYZ024A firmware from the host MCU.

This sample application works in a configuration that uses the EK-RA6M5 board with RA6M5 as the host MCU and connects the PMOD™ Expansion Board for RYZ024A to the PMOD connector. The RYZ024A firmware file is stored on a USB flash drive that can be connected to the USB FS connector on the EK-RA6M5 board. The firmware can then be transferred from the USB flash drive to the RYZ024A to complete the upgrade.

Target Device

RYZ024A

EK-RA6M5

Related Documents

- RA6M5 Group RYZ024A PMOD LTE Connectivity with RA6M5 MCU Quick Start Guide (R21QS0007)
- RYZ024 Module System Integration Guide (R19AN0101)
- RA6M5 Group User's Manual: Hardware (R01UH0891)
- RA6M5 Group Evaluation Kit for RA6M5 Microcontroller Group EK-RA6M5 v1 User's Manual (R20UT4829)
- Renesas Flexible Software Package (FSP) User's Manual (R11UM0155)

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Contents

1. Overview

During a product lifetime, at least one modem software upgrade will most likely be required. There are three types of firmware upgrade methods for RYZ024A:

- Connect to LTE network and upgrade wirelessly (Firmware Upgrade Over-the-Air (FOTA))
- Upgrade from PC
- Upgrade from the control microcomputer (Host MCU)

This application note describes the third method and shows how to upgrade from the control microcomputer (Host MCU) using the RA6M5. The configuration uses the EK-RA6M5 board with the RA6M5 MCU as the host MCU and the PMOD Expansion Board for RYZ024A is connected to the PMOD connector. The RYZ024A firmware file is stored on a USB flash drive and connected to the USB FS connector on the EK-RA6M5 board. The firmware can be transferred from the USB flash drive to the RYZ024A to upgrade.

Figure 1. shows a configuration diagram of the firmware upgrade sample application.

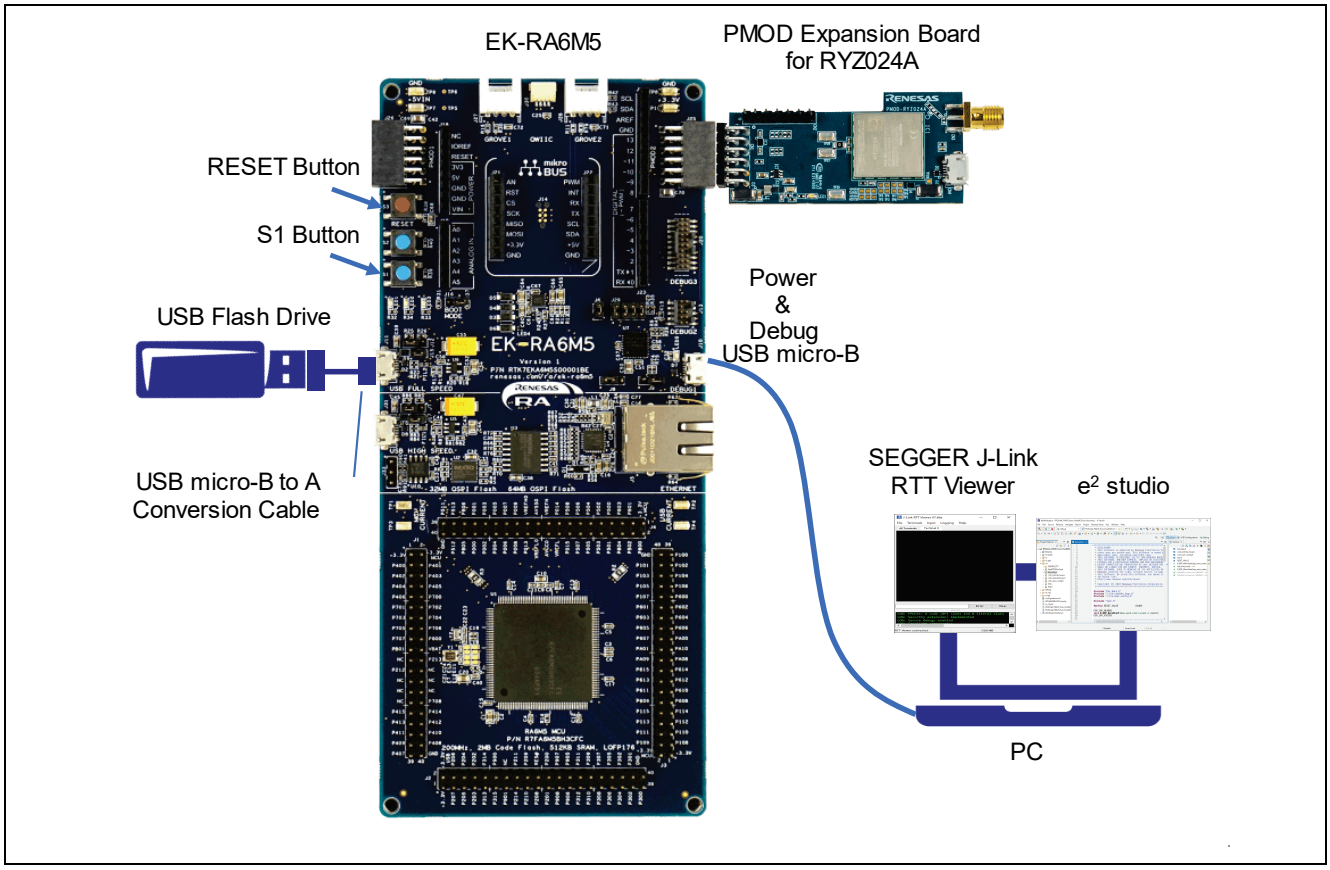

Figure 1. Firmware Upgrade Sample Application Configuration Diagram

2. Operating Environment

2.1 Hardware

The hardware requirements used in the sample application are shown below.

Table 1. Hardware Requirements

Hardware	Description
PMOD Expansion Board for RYZ024A	RTKYZ024A0B00000BE
EK-RA6M5	RTK7EKA6M5S00001BE
USB Flash Drive	10 MB or more
Windows® 10 PC	---
USB Cable	• For EK-RA65M USB Debug connecter (micro-B) • For USB Flash Drive (USB micro-B to A Conversion)

2.2 Software

The software requirements used in the sample application are shown below.

Table 2. Software Requirements

Software	Version
e2 studio	2023-04
GCC Compiler	10.3.1
FSP	4.4.0
SEGGER J-Link RTT Viewer	V7.88 (It is used in the execution log display for operation check.) (Download J-Link RTT Viewer)

2.3 Microcontroller Peripheral Functions

The microcontroller peripheral functions used in the sample application are shown below.

Table 3. Microcontroller Peripheral Functions

Peripheral function name		Description
Serial Communication Interface	SCI0(UART0)	UART communication with RYZ024A Baudrate : 115200 bps Data length : 8 bit Parity : None Stop bit : 1 bit Flow control : Hardware CTS/Software RTS RTS : P412 CTS : P413
Low power Asynchronous General Purpose Timer	AGT0	UART communication timeout with RYZ024A
	AGT1	LED blinking cycle
USB2.0 Full-Speed Module	USBFS	Communication with the USB flash drive where the firmware file is stored.
I/O Port	P404	Reset pin control of RYZ024A
	P412	RTS signal used for UART communication with RYZ024A.
	P413	CTS signal used for UART communication with RYZ024A.
	P006	User LED1 (Blue)
	P008	User LED3 (Red)
External Interrupt Request	IRQ10	External interrupt request of user button S1

2.4 FSP Modules

The FSP modules used in the sample application are shown below.

Table 4. FSP Modules

Module Type	Module Name	
System	I/O Port	(r_ioport)
Storage	FreeRTOS+FAT	(rm_freertos_plus_fat) (Note)
Storage	Block Media USB	(rm_block_media_usb)
Connectivity	USB HMSC	(r_usb_hmsc)
Connectivity	USB	(r_usb_basic)
Transfer	Transfer	(r_dmac)
Input	External IRQ	(r_icu)
Connectivity	UART	(r_sci_uart)
Timers	Timer, Low-Power	(r_agt)

Note: This program is a bare metal version.

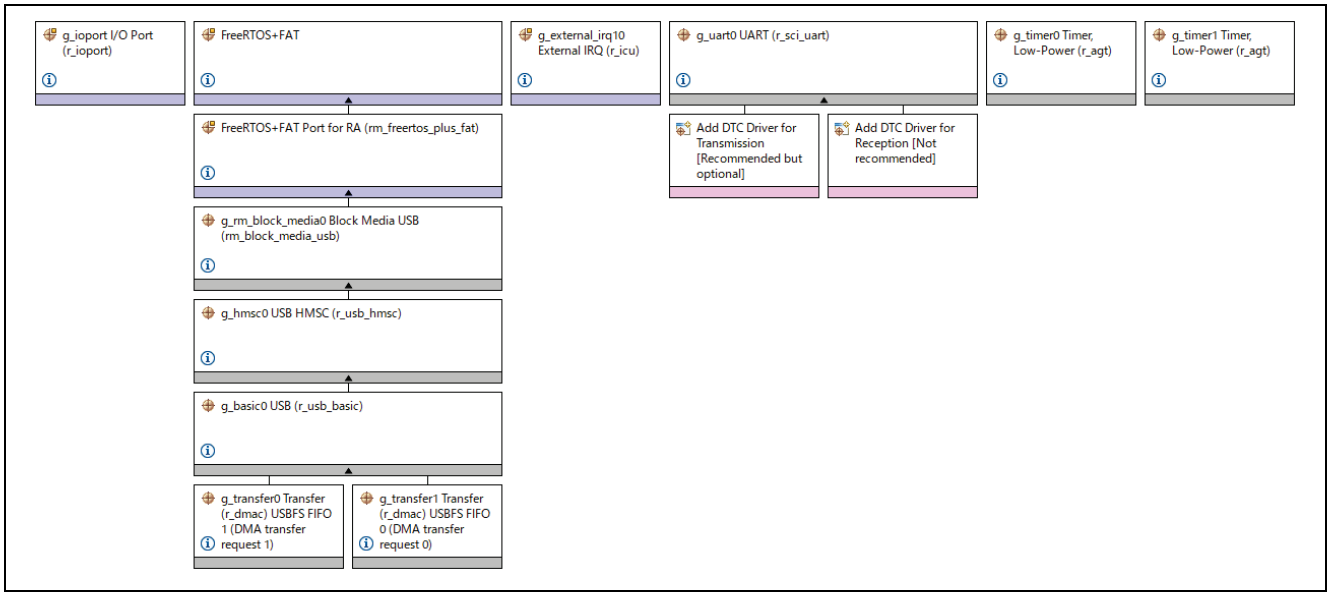

Figure 2. FSP Module Configuration

2.5 Directory/File Structure

Directory/file structure of sample application are shown below.

Table 5. Directory/File Structure

Directory/ File Structure				Description
RYZ024A_FWUP_from_HostMCU\		.api_xml .cproject .project .secure_azone .secure_xml configuration.xml R7FA6M5BH3CFC.pincfg ra_cfg.txt RYZ024A_FWUP_from_HostMCU Debug_Flat.jlink RYZ024A_FWUP_from_HostMCU Debug_Flat.launch		Project files for GCC. Files for RA configurator.
	.settings\	com.renesas.cdt.ddsc.content.prefs com.renesas.cdt.ddsc.contentgen.options.prefs com.renesas.cdt.ddsc.packs.componentfiles.prefs com.renesas.cdt.ddsc.settingseditor.prefs com.renesas.cdt.ddsc.threads.configurator.prefs com.renesas.cdt.managedbuild.gnuarm.prefs CoverageSetting.xml DebugVirtualConsoleSetting.xml e2studio_project.prefs IORegisterSetting.xml language.settings.xml org.eclipse.cdt.core.prefs org.eclipse.cdt.managedbuilder.core.prefs		e^2 studio setting files.
	script\	fsp.ld		Linker setting file.
	src\	hal_entry.c r_lte_ryz024a_fwup.c r_lte_ryz024a_fwup.h r_lte_user_config.h	Firmware upgrade sample application source codes.	

Directory/ File Structure				Description
		FreeRTOSConfig.h	Header files required when using FreeRTOS+FAT without FreeRTOS.	
		SEGGER_RTT\	SEGGER_RTT.c SEGGER_RTT.h SEGGER_RTT_Conf.h SEGGER_RTT_printf.c	SEGGER J-Link RTT Viewer source coeds.

3. How to Use this Project

This section covers how to use the sample application. Refer to Figure 1 for the execution environment.

Please execute this sample application while disconnected from the LTE network.

3.1 Preparation of RYZ024A Firmware

There are two types of RYZ024A firmware files. Full firmware file, which upgrades the entire firmware, and differential firmware file, which upgrades the difference between the current version and the new version. Change one of the firmware files(Note) to the following name and store it in the root directory of the USB memory.

Full firmware file : ryz024a_firmware_full.dup

Differential firmware file : ryz024a_firmware_diff.dup

Note: Firmware files will be provided directly to you by Renesas as needed. Please contact Renesas and get these file(s). Please note that the file will differ depending on the firmware version.

3.2 EK-RA6M5 Jumper Setting

The USB Full Speed interface of EK-RA6M5 is used as a USB Host to connect a USB flash drive. Set the jumper as follows according to *RA6M5 Group Evaluation Kit for RA6M5 Microcontroller Group EK-RA6M5 v1 User's Manual* (R20UT4829).

J12: Jumper on pins 1-2

J15: Open

3.3 Import a Project

The steps to import a sample application project into e² studio are shown below.

1. Launch e² studio, specify the workspace directory, and click the **Launch** button.

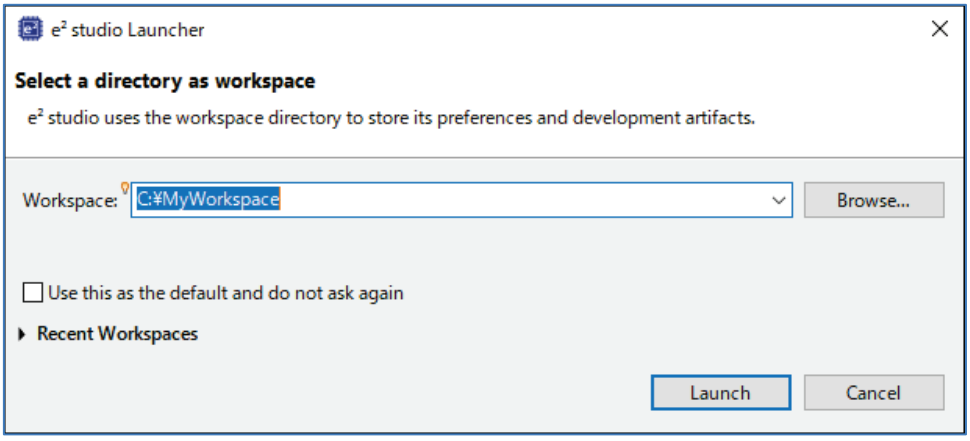

Figure 3. Workspace Selection

2. Select **File** > **Import** ... from the menu bar.

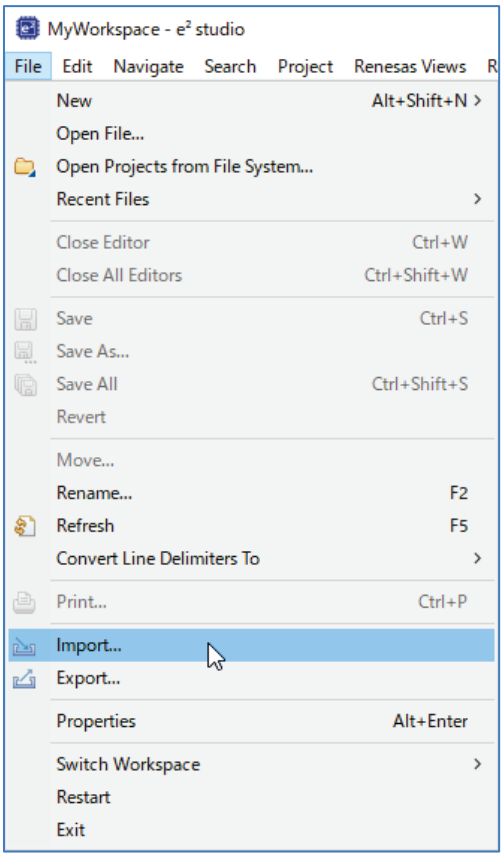

Figure 4. File Menu

3. Select **Existing Projects into Workspace** and click **Next**.

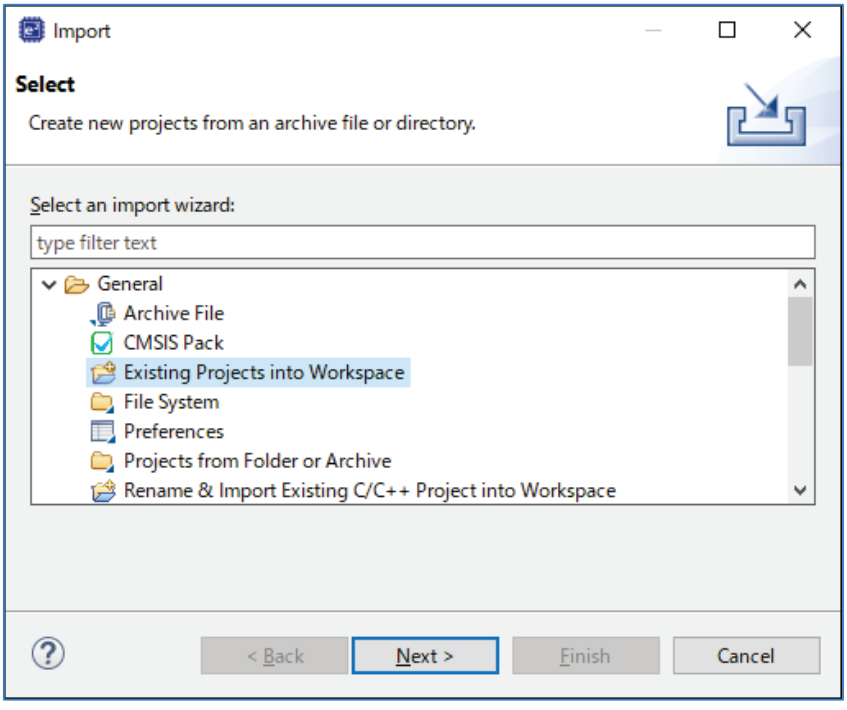

Figure 5. Import Wizard Selection

4. Select **Select root directory**, click **Browse...** and select the directory for your sample project. Click the **Finish** button to import the project.

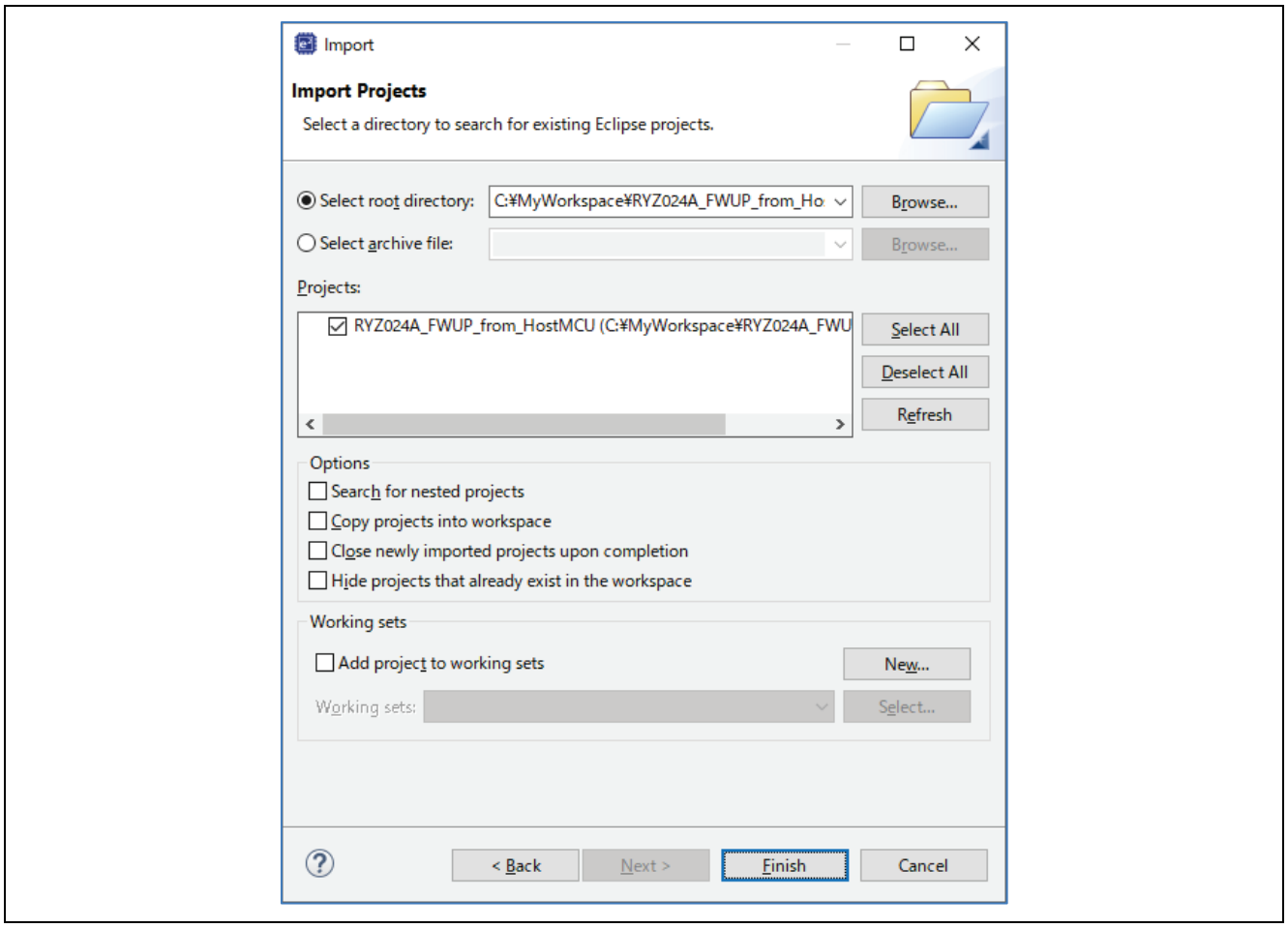

Figure 6. Import Project

3.4 Build and Download

1. Double-click `configuration.xml` to open the FSP Configuration window.

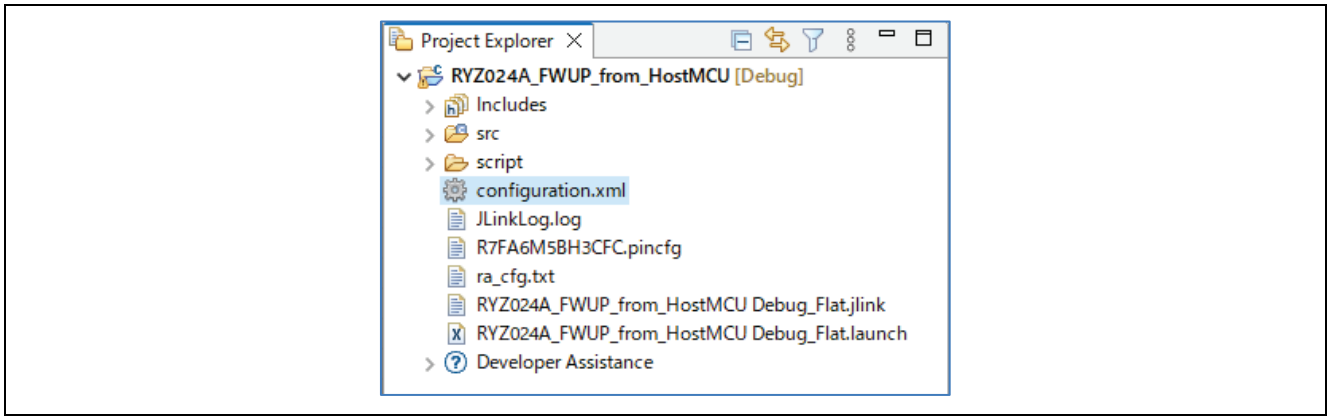

Figure 7. Configuration.xml

2. Click the **Generate Project Content** icon in the upper right corner of the FSP Configuration window. The required files are extracted from the FSP, and the source and header files are added to the project.
3. Select **Project > Build Project** from the menu bar or click the **Build** icon to build the project.
4. Click the debug icon to launch the project. When the project starts, the sample application will be downloaded to EK-RA6M5.

3.5 Launch J-Link RTT Viewer

1. Launch J-Link RTT Viewer, set as follows, and click **OK**.

   Connection to J-Link : USB

   Specify Target Device : R7FA6M5BH

   Target Interface & Speed : SWD, 4000 kHz

   RTT Control Block : Address, 0x200001fc (Note)

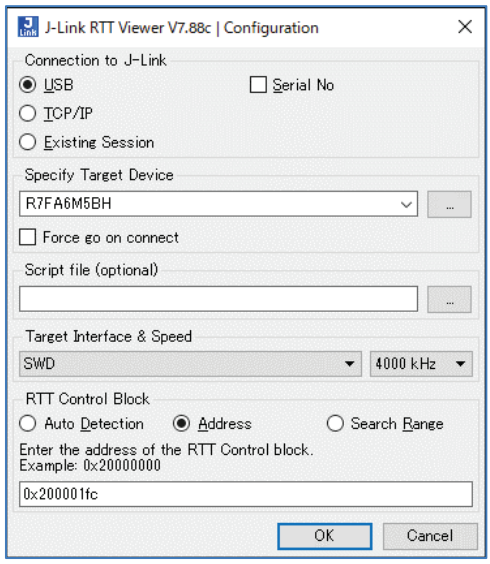

Figure 8. J-Link RTT Viewer Configuration

Note: The RTT Control Block Address sets the `.bss._SEGGER_RTT` section address of the map file generated in the Debug directory.

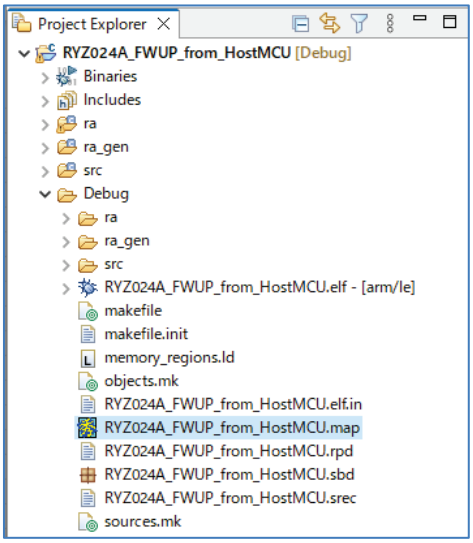

Figure 9. RTT Control Block Address

3.6 Firmware Upgrade Execution

A. Click the **Resume** icon in the debug perspective to run the sample application.

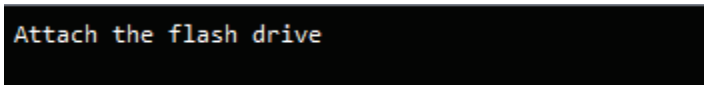

Figure 10. Sample Application Execution

B. Connect the USB flash drive to the USB micro-B to A conversion cable connected to the USB FS connector of the EK-RA6M5. The RYZ024A firmware file stored on the USB flash drive will be found and the file size will be displayed.

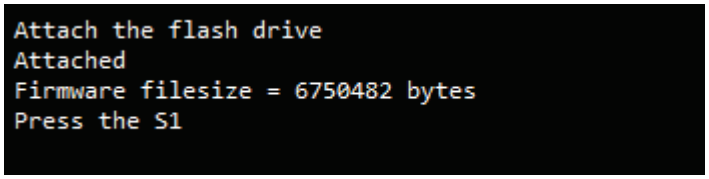

Figure 11. RYZ024A Firmware File Detection

C. Press the **S1** button. The firmware upgrade will be executed.
(Below are the results of running an upgrade using the full firmware file.)

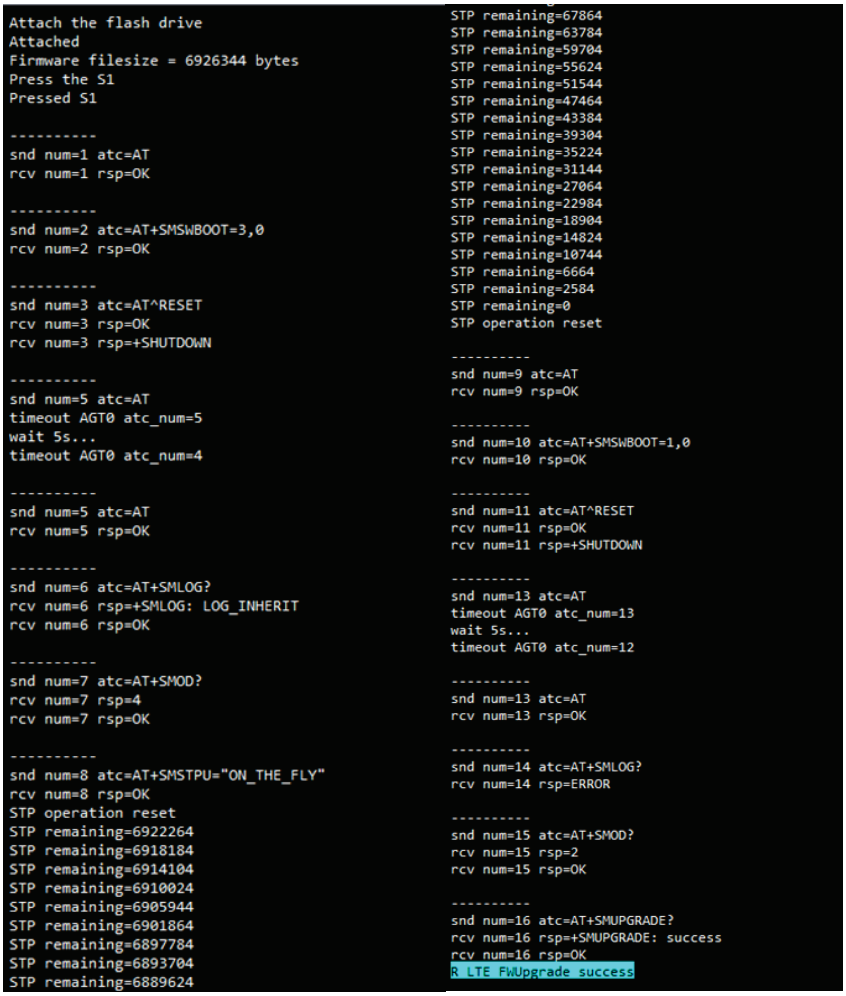

Figure 12. Firmware Upgrade Execution

4. Program Processing

Firmware upgrade is performed by calling **R_LTE_FWUpgrade** function. When the firmware file of RYZ024A stored in the USB flash drive is detected and the S1 button is pressed, AT command processing starts.

In AT command processing, AT commands are sent in the order shown in section 4.2.1, AT Command Flow and responses are received. Then, instruct RYZ024A to execute the firmware upgrade.

Firmware data transfer processing uses the Simple Transfer Protocol (STP) shown in section 4.3, Firmware Data Transfer Processing to send firmware data to RYZ024A.

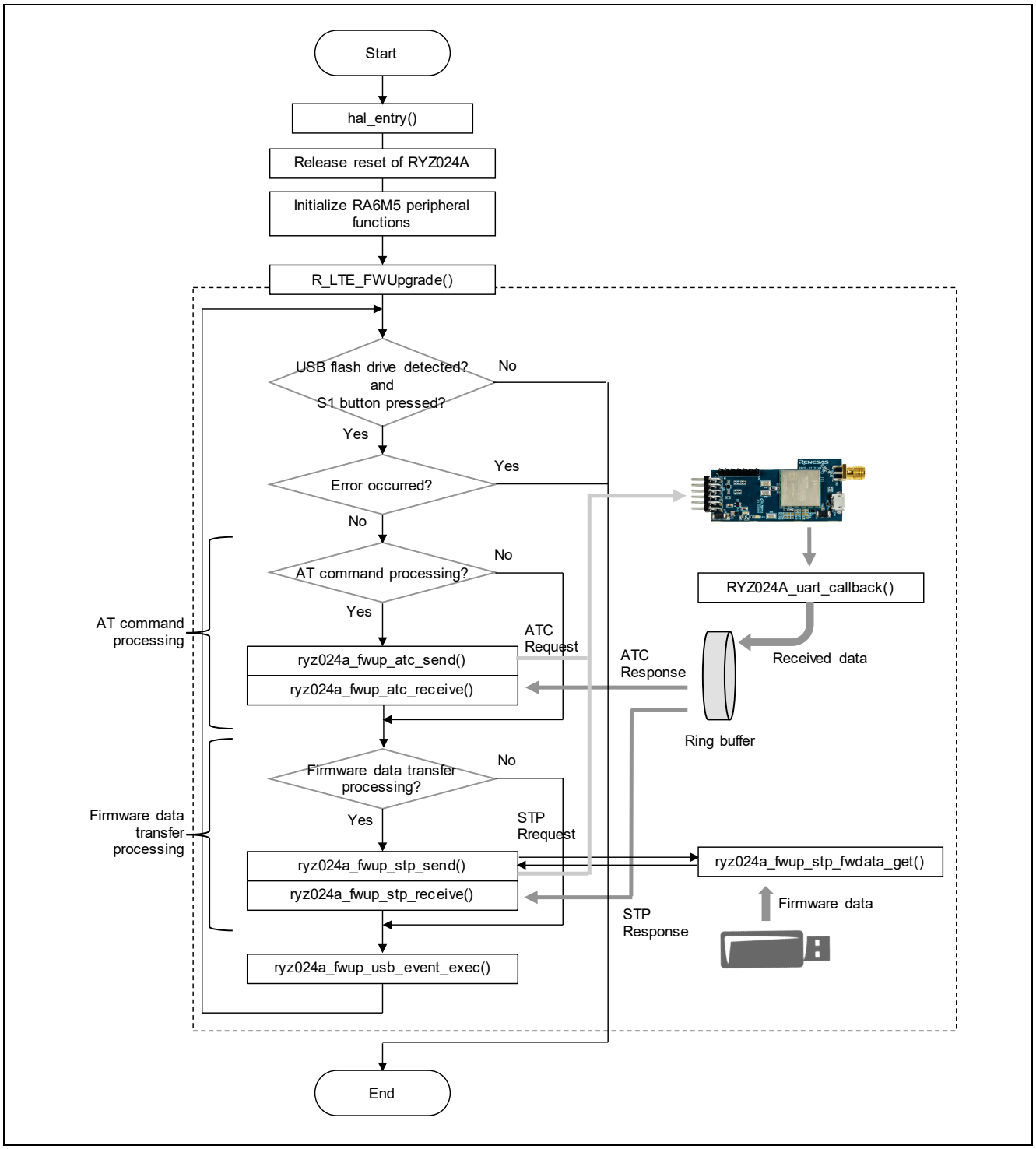

Figure 13. Firmware Upgrade Program Processing Overview Diagram

4.1 API

4.1.1 User API

4.1.1.1 Firmware Upgrade Function

(1) R_LTE_FWUpgrade

Function	Upgrade the firmware of RYZ024A.
Arguments	None
Return	Success: LTE_SUCCESS (successful firmware upgrade) Error : LTE_ERR_FWUPGRADE (firmware upgrade failure) LTE_ERR_NOT_FOUND_FWFILE (firmware file not found) (Refer to `r_lte_ryz024a_fwup.h` for error definition macros.)

4.1.2 Internal Processing Function

4.1.2.1 AT Command Processing Function

(1) ryz024a_fwup_atc_send

Function	Send an AT command to RYZ024A. For the AT command to be sent, refer to section 4.2.1, AT Command Flow.
Arguments	None
Return	None

(2) ryz024a_fwup_atc_receive

Function	The response of the AT command is received from RYZ024A and the result is evaluated. For the response to be received, refer to section 4.2.1, AT Command Flow. If the following error occurs, re-send the same AT command 5 times. If a normal response cannot be received during retransmission, reset RYZ024A and re-start from the beginning of AT command processing. If the same error occurs again, the firmware upgrade will fail. An invalid response was received. No response was received for 10 seconds.
Arguments	None
Return	None

4.1.2.2 Firmware Data Transfer Processing Function

(1) ryz024a_fwup_stp_send

Function	Send an STP request to RYZ024A. For details on the protocol, refer to section 4.3, Firmware Data Transfer Processing.
Arguments	None
Return	None

(2) ryz024a_fwup_stp_receive

Function	The STP response is received from RYZ024A and the result is evaluated. For details on the protocol, refer to section 4.3, Firmware Data Transfer Processing. If the following error occurs, reset the same RYZ024A and re-execute from the beginning of AT command processing. If the same error occurs again, the firmware upgrade will fail. An invalid response was received. No response was received for 10 seconds.
Arguments	None
Return	None

(3) ryz024a_fwup_stp_fwdata_get

Function	Gets the firmware data of the specified size from the firmware file.
Arguments	Firmware data storage buffer pointer (output) Data size to get (input)
Return	None

4.2 AT Command Processing

4.2.1 AT Command Flow

The AT command flow for full firmware and differential firmware upgrades is shown below.

(1) Full Firmware

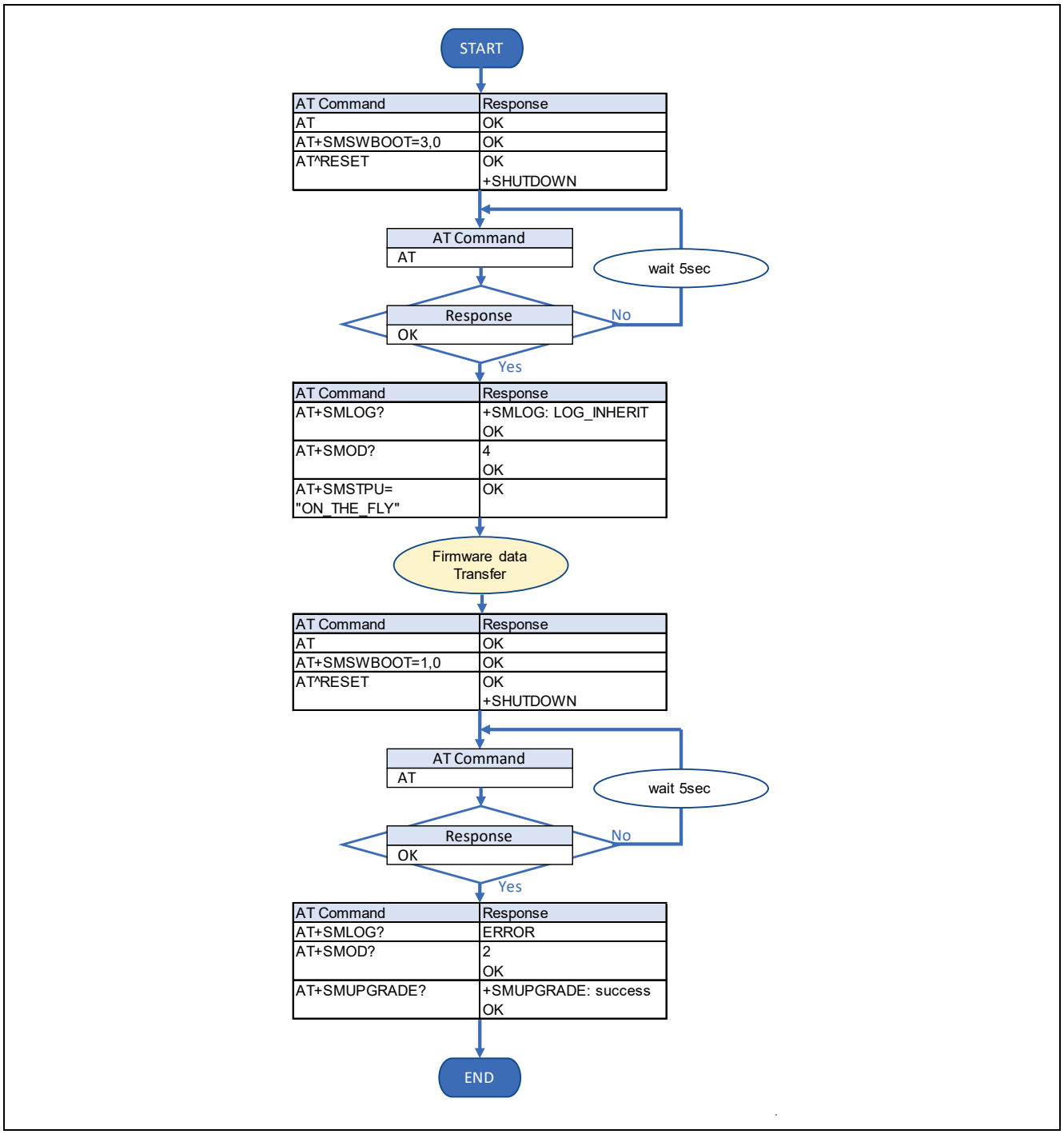

Figure 14. Firmware Upgrade Program Processing Overview Diagram

(2) Differential Firmware

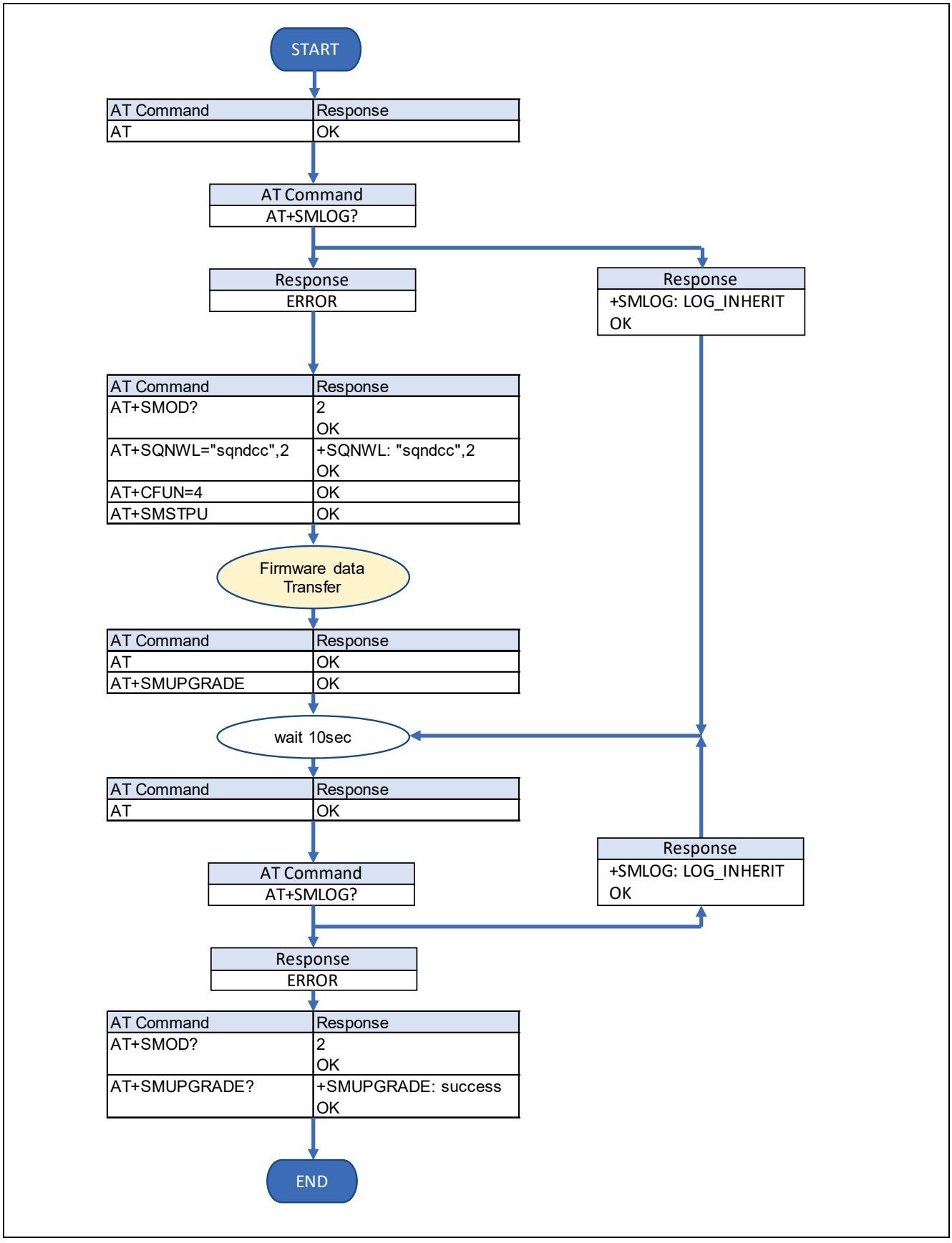

Figure 15. AT Command Flowchart (Differential firmware)

4.2.2 AT Command

Outlines the AT commands used in the firmware upgrade.

Table 6. AT Command

AT Command	Description
AT+SMLOG?	Returns the firmware upgrade status.
AT+SMOD?	Returns the boot mode.
AT+SQNWL	Controls the transition to sleep mode.
AT+CFUN	Select the Mobile Termination (MT) functional level.
AT+SMSTPU	Starts Simple Transfer Protocol (STP) transfer.
AT+SMUPGRADE	Execute firmware upgrade.
AT+SMSWBOOT	Boots the device in the specified mode.

4.3 Firmware Data Transfer Processing

The Firmware data transfer process uses Simple Transfer Protocol (STP) to send firmware data to the RYZ024A. Communication is performed using the request packet sent from the host MCU to the RYZ024A and the response packet sent from the RYZ024A to the host MCU.

4.3.1 Packet Configuration

4.3.1.1 STP Packet

This section gives the configuration of the STP packet. The 16 bytes excluding the payload of the following configuration is called the STP header.

Table 7. STP Packet Configuration

Name	Size	Description
signature	4	Request : 0x66617374 ("fast") Response : 0x74736166 ("tsaf")
operation (op)	1	0x00 : reset 0x01 : open session 0x02 : transfer block command 0x03 : transfer block Response operation is OR with 0x80.
session ID (sid)	1	Set to 0 on reset, set to 1 once session is open.
payload length (plen)	2	Payload length
transaction ID (tid)	4	Transaction ID, set to 0 on reset, then incremented after each answer.
full header checksum (hcrc16)	2	Request : full header checksum Response : 0
payload checksum (pcrc16)	2	Payload checksum or 0 if no payload.
payload	-	Payload data Refer to "4.3.1.2 Payload" for the data structure.

4.3.1.2 Payload

The Payload configuration is shown below. The Payload used depends on the operation status.

(1) Open Session Operation Payload (Response)

This payload is added in the response of open session operation.

Table 8. Open Session Payload Configuration

Name	Size	Description
success	1	Indicate if session has been open with success (1) or not (0).
version	1	protocol version, always 1.
max transfer size	2	max size for STP header + payload.

(2) Transfer Block Command Operation Payload (Request)

This payload is added in the transfer block command operation request.

Table 9. Transfer Block Command Payload Configuration

Name	Size	Description
block size	2	block size to transfer.

(3) Transfer Block Operation Payload (Request)

This payload is added in the transfer block operation request.

Table 10. Transfer Block Operation Request Payload Configuration

Name	Size	Description
firmware data	-	firmware data. size = max transfer size - STP header

(4) Transfer Block Operation Payload (Response)

This payload is added in the transfer block operation response.

Table 11. Transfer Block Command Response Payload Configuration

Name	Size	Description
residue	2	always 0.

4.3.1.3 Checksum

The checksum calculation method is shown below.

```
uint16_t ryz024a_fwup_stp_crc16(const void *input, size_t length)
{
    uint16_t crc = 0;
    const uint8_t *data = (const uint8_t *)input;

    while (length-- > 0)
    {
        crc  = (uint16_t)((0xFF & (crc >> 8)) | (crc << 8));
        crc ^= (uint16_t)*data++;
        crc ^= (uint16_t)((crc & 0xff) >> 4);
        crc ^= (uint16_t)(crc << 12);
        crc ^= (uint16_t)((uint8_t)(crc & 0xff) << 5);
    }
    return crc;
}
```

Figure 16. Checksum calculation method

4.3.2 Operation Flow

This section describes the operation flow when sending firmware data by STP.

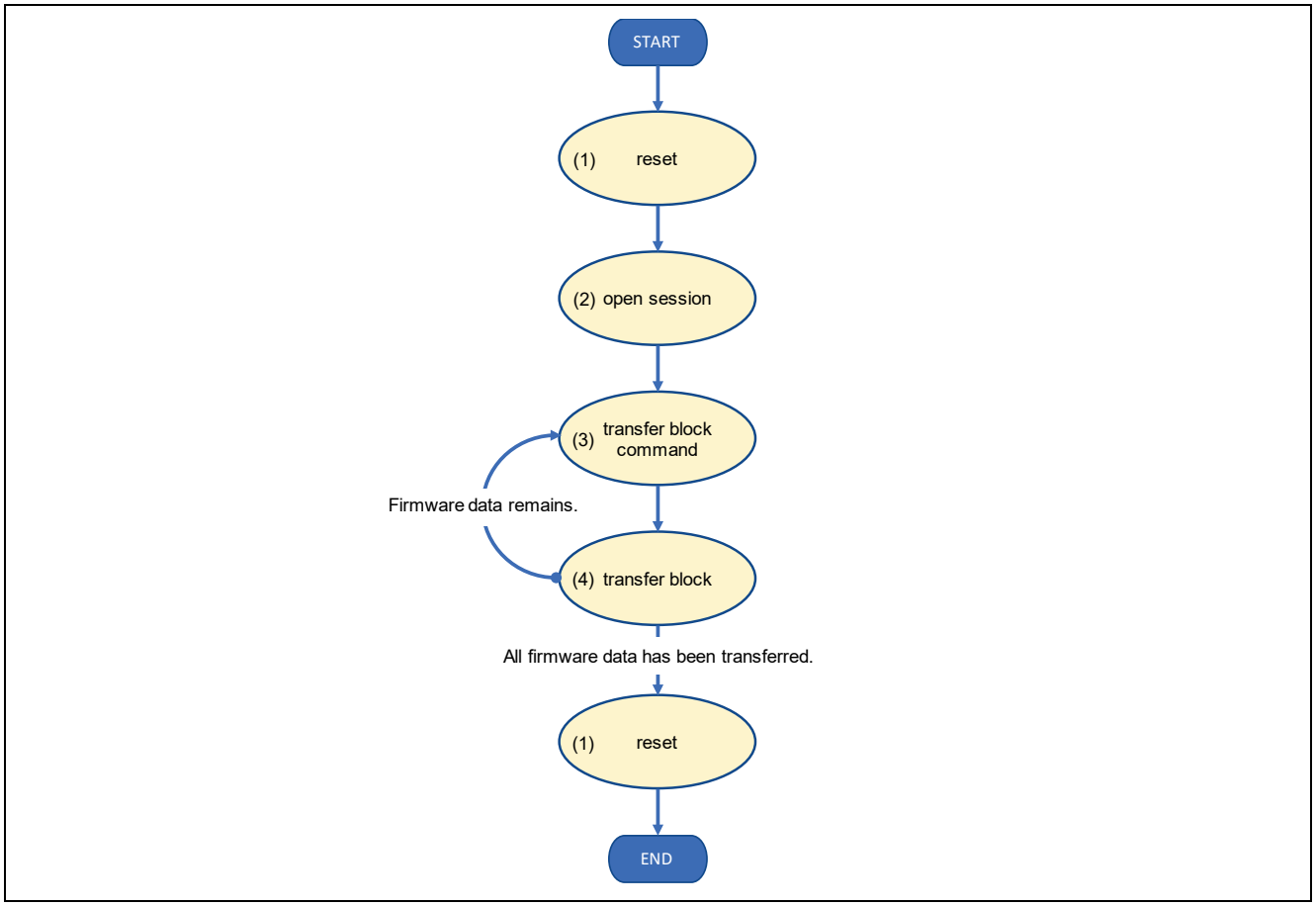

Figure 17. Operation Flowchart

(1) Reset

- Reset an open remote session.
- Reset sid and tid to 0.
- There is no request payload.
- There is no response payload.

Request packet

signature				op	sid	plen		tid				hcrc16		pcrc16		payload
66	61	73	74	00	00	00	00	00	00	00	00	8A	E3	00	00	-

(Hexadecimal)

Response packet

signature				op	sid	plen		tid				hcrc16		pcrc16		payload
74	73	61	66	80	00	00	00	00	00	00	00	00	00	00	00	-

(Hexadecimal)

(2) Open Session

- Open session with peer and get the session parameters "Open session operation payload (Response)".
- Set sid and tid to 1. Increment tid once the response is received.
- There is no request payload.
- Get the session parameters "Open session operation payload (Response)" in the response.

Request packet

signature				op	sid	plen		tid				hcrc16		pcrc16		payload
66	61	73	74	01	01	00	00	00	00	00	01	FB	8E	00	00	-

(Hexadecimal)

Response packet

signature				op	sid	plen		tid				hcrc16		pcrc16		payload			
																success	version	max transfer size	
74	73	61	66	81	01	00	04	00	00	00	01	00	00	47	62	01	01	20	00

(Hexadecimal)

(3) Transfer Block Command

- Instructs RYZ024A to receive firmware data. Increment tid once the response is received.
- Send "Transfer block command operation payload (Request)" in the request.
- There is no response payload.

Request packet

signature				op	sid	plen		tid				hcrc16		pcrc16		payload	
																block size	
66	61	73	74	02	01	00	02	00	00	00	02	E1	18	FF	21	0F	F0

(Hexadecimal)

Response packet

signature				op	sid	plen		tid				hcrc16		pcrc16		payload
74	73	61	66	82	01	00	00	00	00	00	02	00	00	00	00	-

(Hexadecimal)

(4) Transfer Block

- Send the firmware data to RYZ024A. Increment tid once the response is received.
- Sends the firmware data "Transfer block operation payload (Request)" in the request.
- Get a "Transfer block operation payload (Response)" in the response.

Request packet

signature				op	sid	plen		tid				hcrc16		pcrc16		payload
																firmware data
66	61	73	74	03	01	0F	F0	00	00	00	03	D2	3D	xx	xx	xx xx xx xx xx...

(Hexadecimal)

Response packet

signature				op	sid	plen		tid				hcrc16		pcrc16		payload	
																residue	
74	73	61	66	83	01	00	02	00	00	00	03	00	00	00	00	00	00

(Hexadecimal)

5. Appendix

5.1 Change Operating Parameters

5.1.1 Differential Firmware Upgrade Timeout Time

Differential firmware upgrade requires several minutes to complete after transferring the differential firmware data to the RYZ024A. If timeouts occur during firmware upgrade, change the values defined in the following table.

Table 12. AT Differential Firmware Upgrade Timeout Time

Name	Value	Description
DIFF_UPGRADE_TO_COUNT_MAX	18	Differential firmware upgrade timeout time. unit: 10 sec For example, 10 sec * 18 = 180 sec

5.1.2 Software Wait Time Until AT Command is Sent

After receiving the AT command response, software waits for about 20 ms before sending the next AT command. If you change the host MCU and need to change the wait value, change the value defined in the following table.

Table 13. Software Wait Time until AT Command is Sent

Name	Value	Description
ATC_SEND_WAIT	20	Software wait time until AT command is sent. unit: 1 msec For example, 1 msec * 20 = 20 msec

5.2 AT Commands Definition

This section describes the AT commands used in the firmware upgrade.

5.2.1 AT+SMSWBOOT

Description:

This command forces the device to boot in mode <mode> (FFF, FFH, Updater or Recovery).

Syntax:

Command	Possible Response(s)
AT+SMSWBOOT=<mode>[,<reboot>]	OK

Parameters:

<mode>: integer 0, 1, 2 or 3. Device start-up mode at next boot

0: FFH

1: FFF

2: UPDATER

3: RECOVERY

<reboot>: integer 0 or 1. Automatic device reboot after <mode> change

0 (default): no reboot

1: reboot after the OK response

5.2.2 AT+SMOD?

Description:

This command returns the boot mode.

Syntax:

Command	Possible Response(s)
AT+SMOD?	<mode>

Parameters:

<mode>: Integer. Device start-up mode at next boot

0: FFH

1: FFF

2: UPDATER

3: RECOVERY

4: OTHER

5.2.3 AT+SMUPGRADE

Description:

AT+SMUPGRADE parses the `.dup` file and directly flashes the data into the corresponding regions depending on which boot mode the module is:

- FFH: Upgrade all regions and filesystem
- RECOVERY: Upgrade all regions and filesystem
- FFF: Upgrade UPDATER and BOOTROM regions
- UPDATER: Upgrade FFF region and filesystem

When in FFF, all authorized regions are upgraded before the module reboots in UPDATER mode to

finish the execution of the `.dup` file. Once the UPDATER mode is over, the module reboots in FFF mode. The SFU tool takes care of both steps, its use is highly recommended for any upgrade.

Syntax:

Command	Possible Response(s)
AT+SMUPGRADE	-
AT+SMUPGRADE?	Upgrade report

5.2.4 AT+SMLOG?

Description:

This command returns the status of the firmware upgrade.

Syntax:

Command	Possible Response(s)
AT+SMLOG?	+SMLOG=LOG_INHERIT
	ERROR

Parameters:

- +SMLOG=LOG_INHERIT: Firmware is upgrading.
- ERROR: Firmware has been upgraded.

5.2.5 AT+SMSTPU

Description:

This command starts a STP transfer, waiting for an FFF image containing upgrade images.

Syntax:

Command	Possible Response(s)
AT+SMSTPU[="ON_THE_FLY"]	-

Parameters:

none: Normal transfer

ON_THE_FLY: Recovery transfer

5.2.6 AT^RESET

Description:

This command performs a hardware reset.

Syntax:

Command	Possible Response(s)
AT^RESET	Device is reset
-	+SHUTDOWN ... +SYSSTART

Revision History

Rev.	Date	Description	
		Page	Summary
1.0	Aug.16.23	-	Initial Release

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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